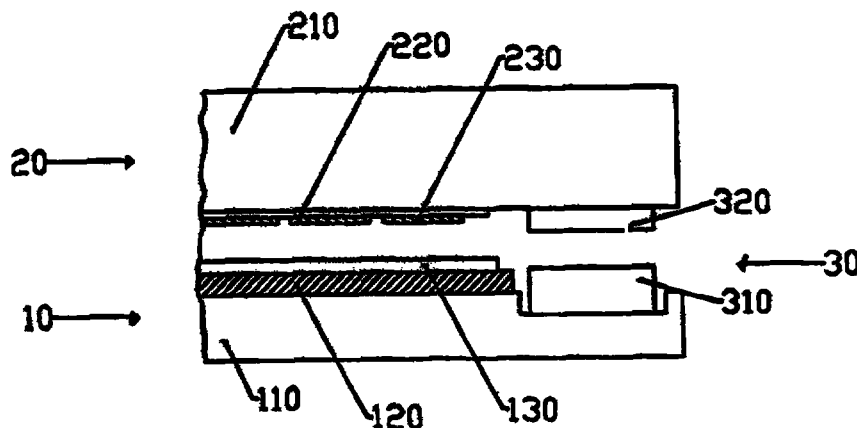




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(54) Title: BONDED ACTIVE MATRIX ORGANIC LIGHT EMITTING DEVICE DISPLAY AND METHOD OF PRODUCING THE SAME



(57) Abstract

The present invention is directed to a method of forming an active matrix organic light emitting device display. The method includes the steps of providing an organic light emitting plate assembly, providing an active matrix assembly, and sealing the organic light emitting plate assembly to the active matrix assembly. The active matrix plate assembly may include a substrate, drive circuitry formed thereon, and at least one pixel pad. The at least one pixel pad may be formed from an electron injector material. The electron injector material may be selected from one of the group consisting of Mg+Al, Al+Li, LiF/Al and CsC. The method may further include the step of cleaning the at least one pixel pad prior to the step of sealing the organic light emitting plate assembly to the active matrix plate assembly. The cleaning step may include the step of ion beam cleaning of at least one pixel pad.